

## LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC2636CMS-LZ10#PBF

(Engineering Calculation)

MSOP

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TOTAL MASS (g): 0.037693

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.	
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002628	1000000	69721.125	
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0	
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.013845	975000	36709.375	
		Iron (Fe)	7439-89-6	0.000355	25000	9418.18847656	
		Phosphorus (P)	7723-14-0	0.000004	300	106.120429993	
		Zinc (Zn)	7440-66-6	0.000010	700	265.301086426	
		Nickel (Ni)	7440-02-0	0.000000	0	0	
		Silicon (Si)	7440-21-3	0.000000	0	0	
		Magnesium (Mg)	7439-96-4	0.000000	0	0	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		<b>Lead Frame Total:</b>			<b>0.014214</b>	<b>1001000</b>	<b>377098.9378</b>
		Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0
Exter. Plating Sn	7440-31-5			0.000710	1000000	18837.0390625	
<b>External Plating Total:</b>					<b>0.000710</b>	<b>1000000</b>	<b>18837.0390625</b>
Inter. Plating Ni	7440-02-0			0.000000	0	0	
Inter. Plating Ag	7440-22-4			0.000086	1000000	2281.58911133	
<b>Internal Plating Total:</b>					<b>0.000086</b>	<b>1000000</b>	<b>2281.58911133</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000836	750000	22179.171875	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		Lead (Pb)	7439-92-1	0.000000	0	0	
		Silica (SiO2)	60676-86-0	0.000000	0	0	
		Indium (In)	7440-74-6	0.000000	0	0	
		Metal Oxide		0.000000	0	0	
		Antimony (Sb)	7440-36-0	0.000000	0	0	
		Resin (EP)		0.000279	250000	7401.96039662	
		<b>Die Attach Total:</b>			<b>0.001115</b>	<b>1000000</b>	<b>29581.0701125</b>
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)		0.002439	130000
Bromine (Br)	40093-93-8			0.000000	0	0	
Silica (SiO2)	60676-86-0			0.015571	830000	411100.34375	
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0	
Metal Hydroxide				0.000057	35000	17430.28125	
Carbon Black (C)	1333-86-4			0.000094	5000	2493.83007812	
<b>Encapsulation Total:</b>					<b>0.018761</b>	<b>1000000</b>	<b>497731.34375</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000179	1000000	4748.88916016	

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